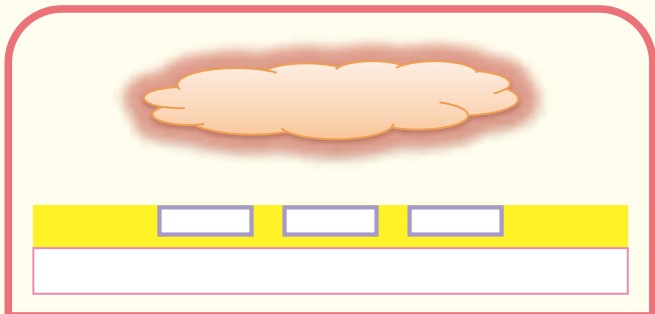


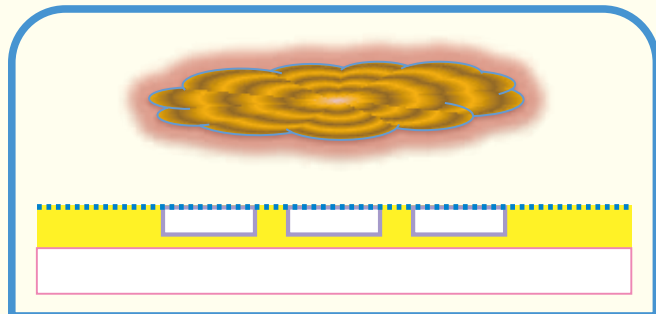
# 電極形成Cuメッキプロセス

## Copper Plating Process

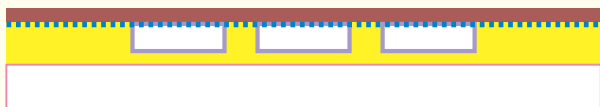
### 1 プラズマ処理 Plasma Treatment



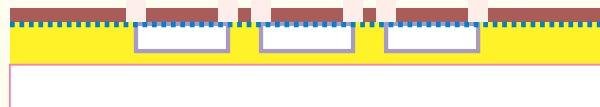
### 2 金属蒸着(シード層形成) Vapor Deposition of Seed Metal



### 3 メッキレジスト塗布※SIPR-7126 Photo Resist Coating



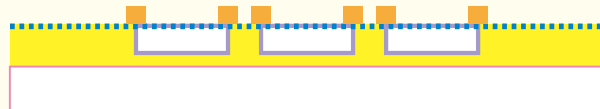
### 4 パターニング:露光・現像(TMAH水溶液) Photo Lithography



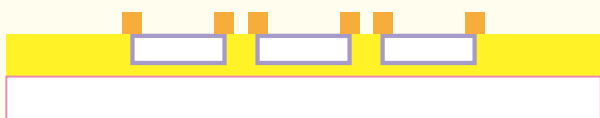
### 5 Cuメッキ 5~10 $\mu$ m (+Ag-Snメッキ) Cu Plating Deposition



### 6 レジスト剥離:PGMEA Resist Stripping



### 7 シード層剥離 Stripping of Metal Seed Layer



### 8 メッキ電極完成 Complete

